Application Insight
March 2023 | Version 1.1

Electronics Assembly Potting
IRS2040-1

Application

Potting of electronic modules for on vehicle use.

Substrates bonded	FR4, electronic components and ABS moulding
Process	Potting
Pre-treatment	None
Curing conditions	▪ Two-part addition cure ▪ 20°C for 48 hours
Resistances required	▪ Fuel and oil resistance ▪ Flame retardant to UL94 V-0 ▪ -40°C to 60°C temperature resistance
Customer benefits	▪ Room temperature cure negates need for curing ovens ▪ Protection of sensitive in vehicle electronics ▪ Cures to a gloss finish, meaning no aesthetic casing required

Product description

IRS 2040-1 Epoxy Potting Compound is a non-toxic general-purpose flame-retardant encapsulating compound. It has a long pot life and can be cured at ambient temperatures or accelerated with heat.

Features and benefits:

- High electrical insulating characteristics
- Good thermal conductivity
- Flame retardant to UL94 V-0 @ 3mm
- Non-toxic
- Cured at room temperature or accelerated with heat

Suitable in applications involving:

- Electronics potting in harsh environments
- Vehicle electronics
- Pipeline inspection systems